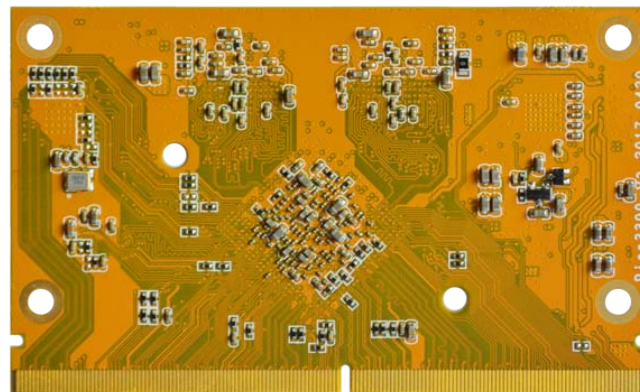


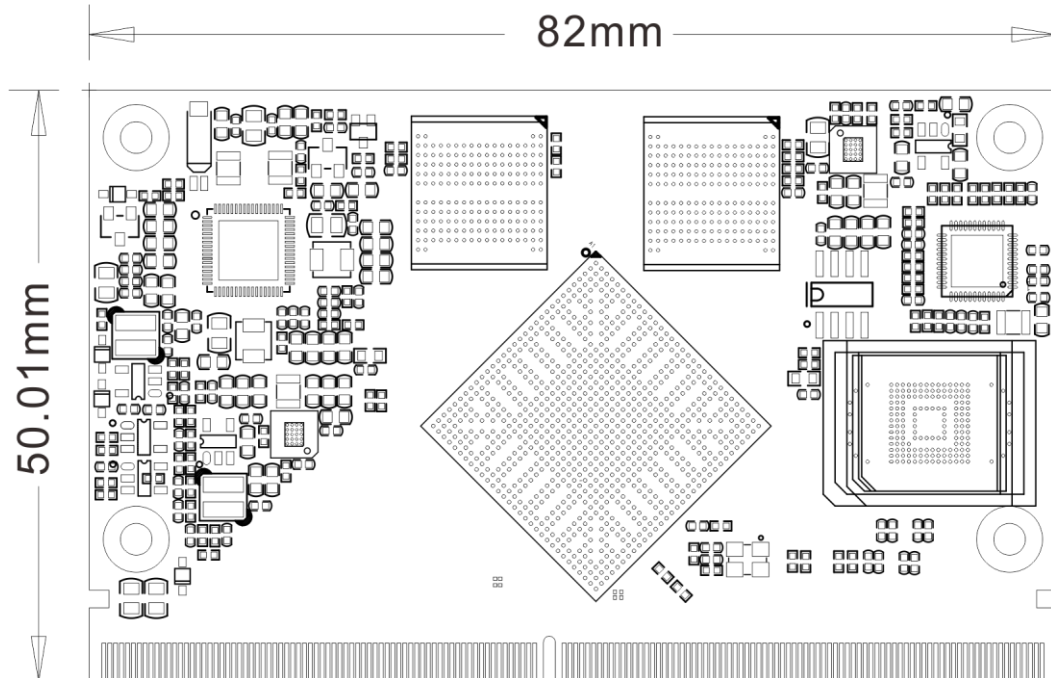
PICO3399 (Rev3)

Interface Connection



1 PCB Dimension

Figure 1. PCB Dimension



2 Interface Connection

The baseboard uses a **MXM 3.0** card edge interface (AS0B826-S55B-*H) for CPU board interfacing.

2.1 MXM 3.0 Card Edge Socket Specifications

Figure 2. MXM 3.0 Socket (on the baseboard)



SPECIFICATIONS

Mechanical

Contact Retention Force: 0.10kg min.
Durability : 25 Cycles

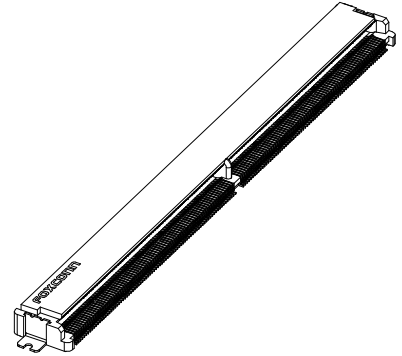
Electrical

Voltage Rating: 25V
Current Rating: 0.5A
Contact Resistance: 55mΩ max.
Dielectric Withstanding Voltage: 200V AC/1 min.
Insulation Resistance: 100MΩ

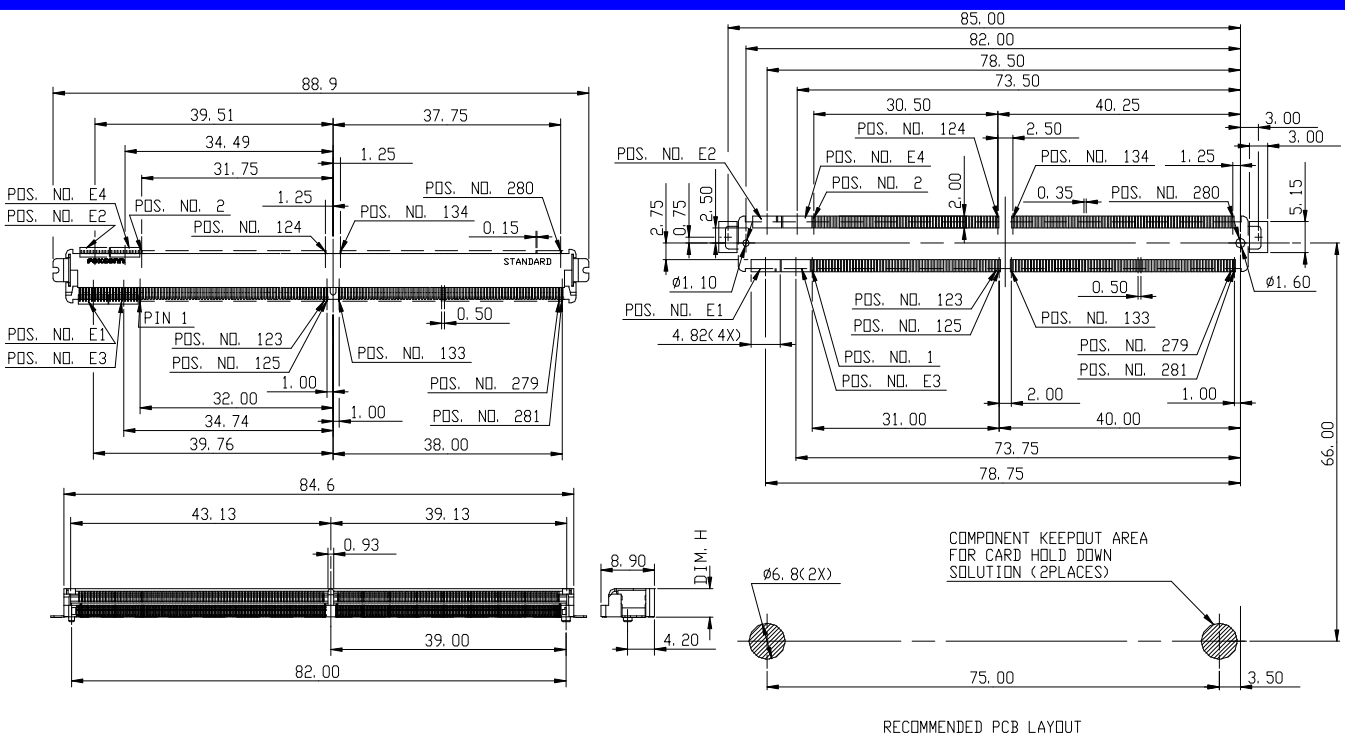
Physical

Housing: Thermoplastic, UL 94V-0 rated in Ivory Color
Contact: Copper alloy
Plating: See "ORDERING INFORMATION"
Metal Spring: Copper alloy
Operating Temperature: -55°C to +85°C

AS Series
4.3mm&5.5mm&
7.8mm Height
SMT Type
0.50mm Pitch
314 Pos.



DRAWING



ORDERING INFORMATION

PRODUCT NO.: A S 0 B 8 2 * - S * * B - * H

Memory Module Socket _____ H=Halogen/Lead Free
 Horizontal Type _____ Package Code
 Single Row _____ 4=Soft Tray
 No. of Pos. _____ 7=Carrier tape
 B8=314Pos. _____ B=Black Color
 SMT Type _____ 43=4.3mm Height
 Contact Area Plating _____ 55=5.5mm Height
 1=Gold Flash _____ 78=7.8mm Height
 6=10u" Gold plating _____ S=Standard Type

ASOB82*-S43B-*H	4.3
ASOB82*-S55B-*H	5.5
ASOB82*-S78B-*H	7.8
P/N	DIM. H